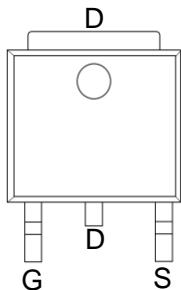


## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

## Application

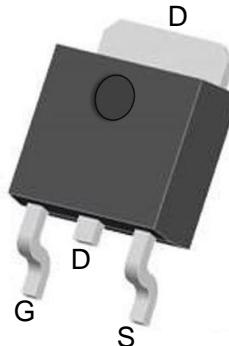
- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch



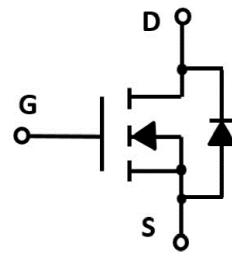
Marking and pin assignment

## Product Summary

V <sub>DS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
30V	9mΩ@10V	60A
	14mΩ@4.5V	



TO-252 top view



Schematic diagram

## Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Rating	Unit
<b>Common Ratings (TC=25°C Unless Otherwise Noted)</b>			
V <sub>DS</sub>	Drain-Source Breakdown Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
T <sub>J</sub>	Maximum Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
I <sub>S</sub>	Diode Continuous Forward Current	T <sub>c</sub> =25°C 60	A

## Mounted on Large Heat Sink

I <sub>DM</sub>	Pulse Drain Current Tested	T <sub>c</sub> =25°C	150	A
I <sub>D</sub>	Continuous Drain Current@GS=10V	T <sub>c</sub> =25°C	60	A
P <sub>D</sub>	Maximum Power Dissipation	T <sub>c</sub> =25°C	27	W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient(*1 in2 Pad of 2-oz Copper), Max.)		60	°C/W

**Electrical Characteristics (TJ=25°C unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ TJ = 25°C (unless otherwise stated)</b>						
$BV_{(BR)DSS}$	Drain-Source Breakdown Voltage	$VGS=0V, ID=250\mu A$	30	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$VDS=30V, VGS=0V$	--	--	1.0	uA
$I_{GSS}$	Gate-Body Leakage Current	$VGS=\pm 20V, VDS=0V$	--	--	$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$VDS=VGS, ID=250\mu A$	1.0	1.5	2.5	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$VGS=10V, ID=15A$	--	6	9	mΩ
		$VGS=4.5V, ID=15A$	--	9	14	mΩ

**Dynamic Electrical Characteristics @ TJ = 25°C (unless otherwise stated)**

$C_{ISS}$	Input Capacitance	$VDS=15V, VGS=0V, f=1MHz$	--	1300	--	pF
$C_{OSS}$	Output Capacitance		--	180	--	pF
$C_{RSS}$	Reverse Transfer Capacitance		--	110	--	pF

**Switching Characteristics**

$Q_g$	Total Gate Charge	$VDS=20V, ID=12A, VGS=4.5V$	--	14	--	nC
$Q_{gs}$	Gate Source Charge		--	3.5	--	nC
$Q_{gd}$	Gate Drain Charge		--	7	--	nC
$t_{d(on)}$	Turn-on Delay Time	$VDD=12V, ID=5A, VGS=10V, RG=3.3\Omega$	--	5	--	nS
$t_r$	Turn-on Rise Time		--	12	--	nS
$t_{d(off)}$	Turn-Off Delay Time		--	27	--	nS
$t_f$	Turn-Off Fall Time		--	10	--	nS

**Source- Drain Diode Characteristics**

$V_{SD}$	Forward on voltage	$Tj=25^\circ C, Is=10A,$	--	--	1.2	V
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### Typical Operating Characteristics

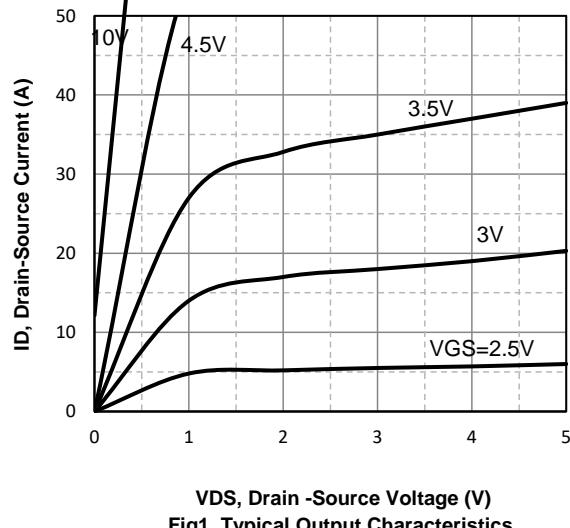


Fig1. Typical Output Characteristics

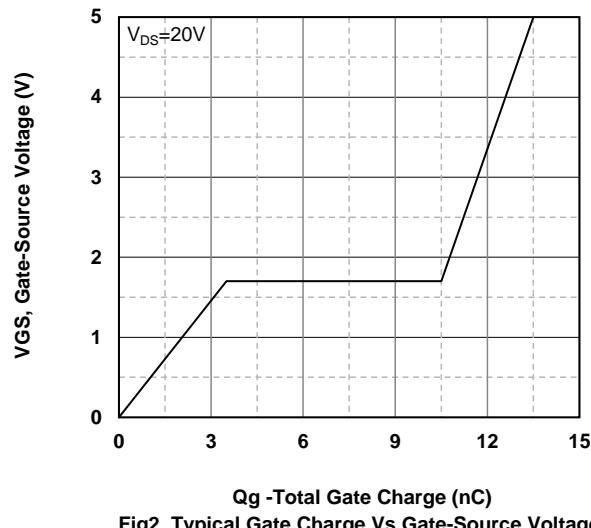


Fig2. Typical Gate Charge Vs. Gate-Source Voltage

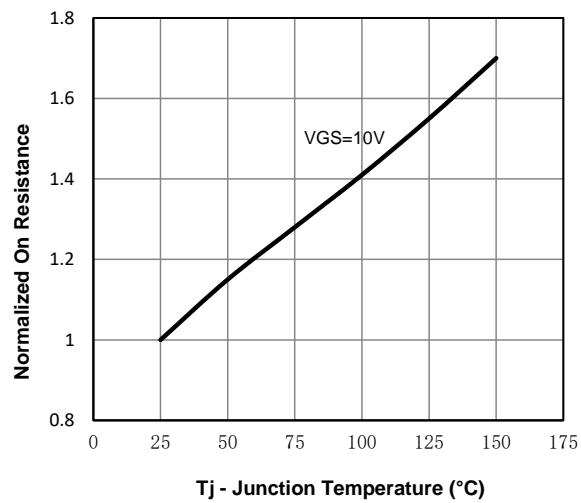


Fig3. Normalized On-Resistance Vs. Temperature

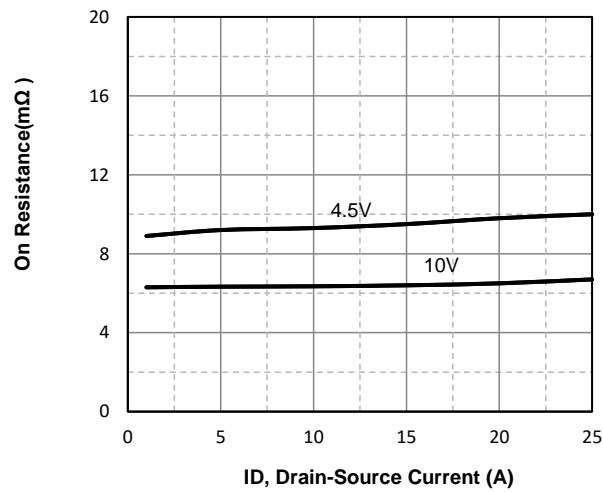


Fig4. On-Resistance Vs. Drain-Source Current

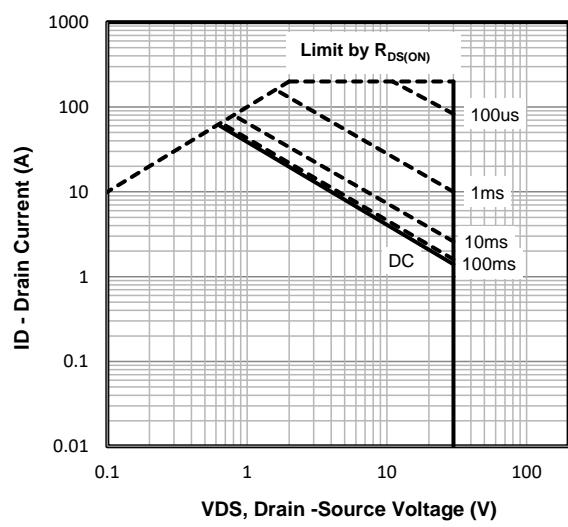


Fig5. Maximum Safe Operating Area

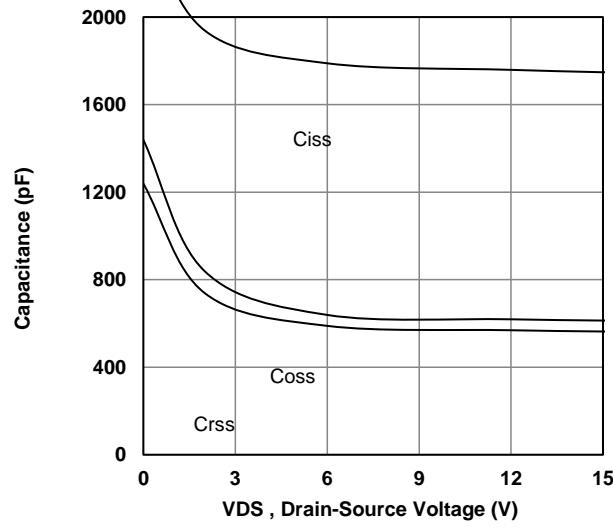
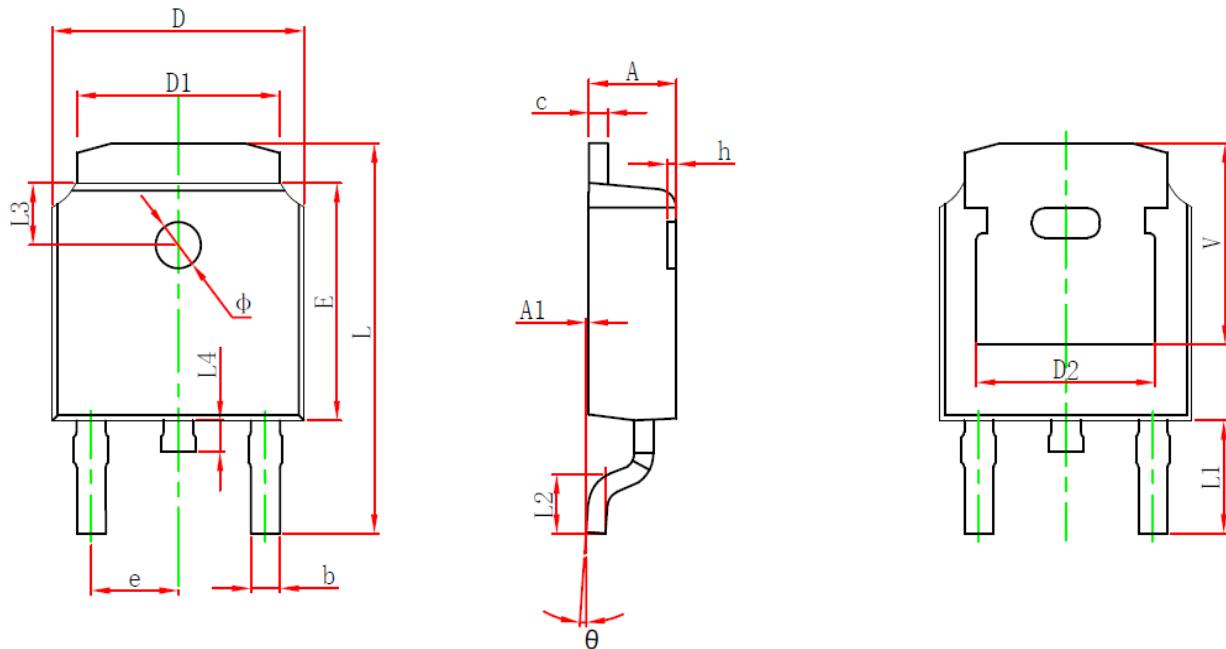


Fig6. Typical Capacitance Vs. Drain-Source Voltage

## TO-252 Package information



Symbol	Dimensions in Millimeters(mm)		Dimensions In Inches	
	Min	Max	Min	Max
A	2.200	2.400	0.087	0.095
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
c	0.450	0.580	0.018	0.023
D	6.500	6.700	0.257	0.265
D1	5.100	5.460	0.202	0.216
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.237	0.245
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.384	0.408
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.040
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250 REF.		0.207 REF.	